

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DT01 Rec'd PCT/PTO 30 DEC 2004

Applicants: H. MATSUURA, et al.

Application No.: TBD

Filed: December 30, 2004

For: ADHESIVE FILM FOR SEMICONDUCTOR USE, METAL  
SHEET LAMINATED WITH ADHESIVE FILM, WIRING  
CIRCUIT LAMINATED WITH ADHESIVE FILM, AND  
SEMICONDUCTOR DEVICE USING SAME, AND METHOD  
FOR PRODUCING SEMICONDUCTOR DEVICE

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

December 30, 2004

Sir:

Please amend the above-identified application, prior to calculation of the filing  
fee, as listed in the following, and as set forth on the following pages:

Amendments to the Claims; and

Remarks are included following the amendments.